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Under the Paperwork Reduction Act of 1985, no persons are required to respond to a collection of information unless it contains a valid OMB control number. Complete If Known Substitute for Form 1449A/PTO **Application Number** 713 852 **INFORMATION DISCLOSURE** Filing Date STATEMENT BY APPLICANT First Named Inventor Asli B. Ucok, et al. **Group Art Unit** 2815 (use as many sheets as necessary) Examiner Name CLARK Sheet of 2 **Attorney Docket Number** UOM 319 PUS

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